

ABSTRACT AMENDMENT(S)

Please insert the following abstract as page 13 of the application:

Method for conditioning of an electronic microcircuit (1) designed for the production of an electronic module which can be glued by means of a simple glue or by soldering. For this purpose the microchip has a geometric shape compatible with a recess in a card (19) provided to accommodate it and has a means serving as a mask (7) compatible with the card. Ultimately this mask also serves to prevent an outflow of a resin coating (14) used to protect a chip (10) included in this type of module. The mask is glued to a support (2) having, on a first face (3), the contact area (4), and on a second face (6) the mask and the chip. The mask includes a window (9) determining the placement of the chip.

Figure 1